

## Applications

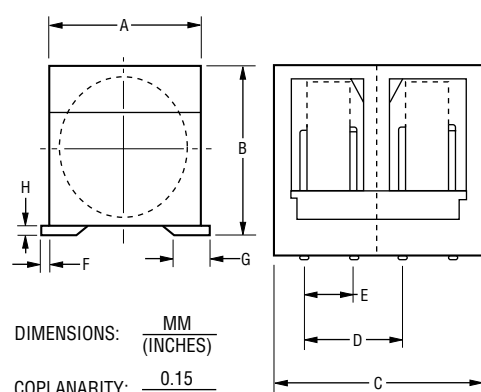
Used as a secondary overcurrent protection device in:

- Customer Premise Equipment (CPE)
- Central Office (CO)
- Access equipment

## CMF-SD Series - Telecom CPTC Resettable Fuses

**BOURNS®**

### Product Dimensions



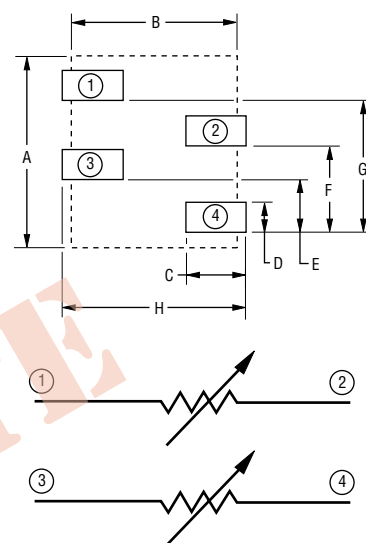
(Reduced value available on request.)

Packaging Options - Tape and Reel:

CMF-SD10, CMF-SD25, CMF-SD35 & CMF-SD50 = 400 pcs. per reel;  
CMF-SD35A & CMF-SD50A = 500 pcs. per reel

| Dim. | CMF-SD10<br>CMF-SD25<br>CMF-SD35<br>CMF-SD50 | CMF-SD35A<br>CMF-SD50A              |
|------|----------------------------------------------|-------------------------------------|
| A    | $\frac{9.00}{(.354)}$ MAX.                   | $\frac{7.15}{(.281)}$ MAX.          |
| B    | $\frac{10.80}{(.425)}$ MAX.                  | $\frac{8.50}{(.355)}$ MAX.          |
| C    | $\frac{10.20}{(.402)}$ MAX.                  | $\frac{8.10}{(.319)}$ MAX.          |
| D    | $\frac{4.88 - 5.28}{(.192 - .208)}$          | $\frac{3.25 - 3.65}{(.128 - .144)}$ |
| E    | $\frac{2.41 - 2.61}{(.095 - .103)}$          | $\frac{2.41 - 2.61}{(.095 - .103)}$ |
| F    | $\frac{0.5}{(.020)}$ MAX.                    | $\frac{0.5}{(.020)}$ MAX.           |
| G    | $\frac{2.5}{(.098)}$                         | $\frac{2.5}{(.098)}$                |
| H    | $\frac{1.0}{(.039)}$                         | $\frac{1.0}{(.039)}$                |

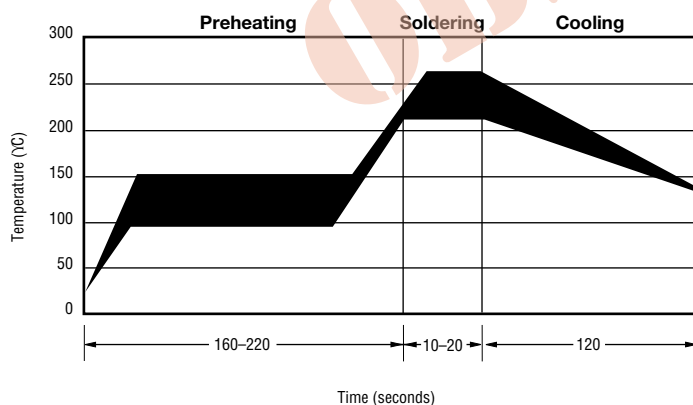
### Recommended Pad Layout



| Dim. | CMF-SD10<br>CMF-SD25<br>CMF-SD35<br>CMF-SD50 | CMF-SD35A<br>CMF-SD50A |
|------|----------------------------------------------|------------------------|
| A    | $\frac{10.0}{(.394)}$                        | $\frac{8.00}{(.315)}$  |
| B    | $\frac{8.80}{(.346)}$                        | $\frac{7.05}{(.278)}$  |
| C    | $\frac{3.20}{(.126)}$                        | $\frac{2.75}{(.108)}$  |
| D    | $\frac{2.00}{(.079)}$                        | $\frac{2.00}{(.079)}$  |
| E    | $\frac{2.60}{(.102)}$                        | $\frac{2.51}{(.099)}$  |
| F    | $\frac{5.00}{(.197)}$                        | $\frac{3.45}{(.136)}$  |
| G    | $\frac{7.60}{(.299)}$                        | $\frac{5.95}{(.234)}$  |
| H    | $\frac{10.0}{(.394)}$                        | $\frac{8.15}{(.321)}$  |

DIMENSIONS:  $\frac{\text{MM}}{(\text{INCHES})}$

### Solder Reflow Recommendations



#### Solder reflow

- Recommended reflow methods: IR, vapor phase oven, hot air oven.
- Devices are not designed to be wave soldered to the bottom side of the board.
- Gluing the devices is not recommended.
- Recommended maximum paste thickness is 0.25 mm (.010 inch).
- Devices can be cleaned using standard industry methods and solvents.

#### Note:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

#### Rework

- A device should not be reworked.

CMF-SD SERIES, REV. Q, 10/19

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.